



RELIABILITY REPORT  
FOR  
MAX1720EUT+T  
PLASTIC ENCAPSULATED DEVICES

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**MAXIM INTEGRATED**

160 RIO ROBLES  
SAN JOSE, CA 95134

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## Conclusion

The MAX1720EUT+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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## I. Device Description

### A. General

The ultra-small MAX1719/MAX1720/MAX1721 monolithic, CMOS charge-pump inverters accept input voltages ranging from +1.5V to +5.5V. The MAX1720 operates at 12kHz, and the MAX1719/MAX1721 operate at 125kHz. High efficiency, small external components, and logic-controlled shutdown make these devices ideal for both battery-powered and board-level voltage conversion applications. Oscillator control circuitry and four power MOSFET switches are included on-chip. A typical MAX1719/ MAX1720/MAX1721 application is generating a -5V supply from a +5V logic supply to power analog circuitry. All three parts come in a 6-pin SOT23 package and can deliver a continuous 25mA output current. For pin-compatible SOT23 switched-capacitor voltage inverters without shutdown (5-pin SOT23), see the MAX828/MAX829 and MAX870/MAX871 data sheets. For applications requiring more power, the MAX860/MAX861 deliver up to 50mA. For regulated outputs (up to  $-2 \times V_{IN}$ ), refer to the MAX868. The MAX860/MAX861 and MAX868 are available in space-saving iMAX packages.

## II. Manufacturing Information

A. Description/Function:	SOT23, Switched-Capacitor Voltage Inverters with Shutdown
B. Process:	S3
C. Fabrication Location:	USA
D. Assembly Location:	Malaysia, Thailand
E. Date of Initial Production:	March 31, 1999

## III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	84-1lmisr4
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1101-0115
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115°C/W
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	230°C/W
M. Multi Layer Theta Jc:	76°C/W

## IV. Die Information

A. Dimensions:	35X57 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Minimum Metal Width:	3.0 microns (as drawn)
E. Minimum Metal Spacing:	3.0 microns (as drawn)
F. Isolation Dielectric:	SiO <sub>2</sub>
G. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

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|-----------------------------------|--|
| A. Quality Assurance Contacts:    | Eric Wright (Reliability Engineering)<br>Brian Standley (Manager, Reliability)<br>Bryan Preeshl (Vice President of QA) |
| B. Outgoing Inspection Level:     | 0.1% for all electrical parameters guaranteed by the Datasheet.<br>0.1% for all Visual Defects.                        |
| C. Observed Outgoing Defect Rate: | < 50 ppm   |
| D. Sampling Plan:                 | Mil-Std-105D   |

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 78 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 14.1 \times 10^{-9}$$

$$\lambda = 14.1 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.04 @ 25C and 0.69 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing

The PX87 die type has been found to have all pins able to withstand an HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.

**Table 1**  
Reliability Evaluation Test Results  
**MAX1720EUT+T**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135C	DC Parameters & functionality	78	0	
	Biased Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.